

Hiroshi Nishikawa

List of Publications by Year in descending order

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159585

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239
all docs

239
docs citations

239
times ranked

1328
citing authors

#	ARTICLE	IF	CITATIONS
1	Electrodeposition of nanocrystalline Cu for Cu-Cu direct bonding. Journal of the Taiwan Institute of Chemical Engineers, 2022, 132, 104127.	5.3	15
2	Surface modification of Cu electroplated layers for Cu-Sn transient liquid phase bonding. Materials Chemistry and Physics, 2022, 277, 125621.	4.0	5
3	Novel transient liquid phase bonding method using In-coated Cu sheet for high-temperature die attach. Materials Research Bulletin, 2022, 149, 111713.	5.2	17
4	Three-dimensional interface and property of SnPb solder joint under extreme thermal shocking. Science and Technology of Welding and Joining, 2022, 27, 186-196.	3.1	12
5	Effect of Low Bi Content on Reliability of Sn-Bi Alloy Joints Before and After Thermal Aging. Jom, 2022, 74, 1751-1759.	1.9	5
6	Adhesion Mechanism between Mold Resin and Sputtered Stainless Steel Ground Films for Electromagnetic Wave Shield Packages. Materials Transactions, 2022, 63, 766-775.	1.2	4
7	Effect of Aluminum Clad Cu Wire Bonds on Power Cycle Lifetime for High Current Density Power Module Packages. Journal of Smart Processing, 2022, 11, 71-77.	0.1	1
8	Microstructure Evolution and Shear Strength of Tin-Indium-xCu/Cu Joints. Metals, 2022, 12, 33.	2.3	7
9	Novel interface regulation of Sn1.0Ag0.5Cu composite solders reinforced with modified ZrO ₂ : Microstructure and mechanical properties. Journal of Materials Science and Technology, 2022, 125, 157-170.	10.7	10
10	Effect of Various Parameters on the Shear Strength of Solid-State Nanoporous Cu Bonding in Cu-Cu Disks for Power Device Packaging. Journal of Electronic Materials, 2022, 51, 3851-3862.	2.2	2
11	Robust shear strength of Cu-Au joint on Au surface-finished Cu disks by solid-state nanoporous Cu bonding. Microelectronic Engineering, 2022, 260, 111807.	2.4	2
12	Synthesis of Hierarchical Structured Cu-Sn Alloy Mesoparticles and Its Application of Cu-Cu Joint Materials. Materials Transactions, 2022, 63, 794-799.	1.2	0
13	Contact Angle Analysis and Intermetallic Compounds Formation Between Solders and Substrates under Formic acid Atmosphere. Journal of Advanced Joining Processes, 2022, , 100118.	2.7	1
14	Mechanical properties of Sn-Bi-Ag low-temperature Pb-free solders. , 2022, , .		0
15	Electromigration Comparison Study of Sn, Ag, and Cu Stripes Fabricated by Electron-Beam Physical Vapor Deposition. , 2022, , .		0
16	High-strength Sn-Bi-based low-temperature solders with high toughness designed via high-throughput thermodynamic modelling. Science and Technology of Welding and Joining, 2022, 27, 572-578.	3.1	4
17	Effect of isothermal aging on properties of In-48Sn and In-Sn-8Cu alloys. , 2022, , .		1
18	Ag die-attach paste modified by WC additive for high-temperature stability enhancement. , 2022, , .		1

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19	Microstructures analysis and quantitative strengthening evaluation of powder metallurgy Ti-Fe binary extruded alloys with (±+1 ²)-dual-phase. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 803, 140708.	5.6	27
20	Electromigration behavior of silver thin film fabricated by electron-beam physical vapor deposition. Journal of Materials Science, 2021, 56, 9769-9779.	3.7	6
21	Effect of Cu addition on the microstructure and mechanical properties of In-Sn-based low-temperature alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 804, 140785.	5.6	11
22	Investigation of FeCoNiCu properties: Thermal stability, corrosion behavior, wettability with Sn-3.0Ag-0.5Cu and interlayer formation of multi-element intermetallic compound. Applied Surface Science, 2021, 546, 148931.	6.1	23
23	Observation of void formation patterns in SnAg films undergoing electromigration and simulation using random walk methods. Scientific Reports, 2021, 11, 8668.	3.3	2
24	Effect of 4.0 mass % Cu addition on microstructure and mechanical properties of In-48Sn alloy. , 2021, , .		0
25	Improvements in mechanical properties of Sn-Bi alloys with addition of Zn and In. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2021, 813, 141131.	5.6	31
26	The voids growth path on Sn-Ag thin film under high current density. , 2021, , .		0
27	Surface Modification of Tetra-needle like ZnO (T-ZnO) and Characterization of Interface Between Sn1.0Ag0.5Cu and NiO Decorated T-ZnO. , 2021, , .		3
28	The effect of solid-state nanoporous Cu bonding for power device. , 2021, , .		1
29	The reliability of ENIG joint bonded by In-coated Cu sheet. , 2021, , .		1
30	Fabrication and characterization of nanoporous copper through chemical dealloying of cold-rolled and annealed Mn-Cu alloy. Journal of Porous Materials, 2021, 28, 1823-1836.	2.6	4
31	Large-area and low-cost Cu-Cu bonding with cold spray deposition, oxidation, and reduction processes under low-temperature conditions. Journal of Materials Science: Materials in Electronics, 2021, 32, 20461-20473.	2.2	2
32	Fabrication of NiO/ZrO ₂ nanocomposites using ball milling-pyrolysis method. Vacuum, 2021, 191, 110370.	3.5	8
33	Interface design and the strengthening-ductility behavior of tetra-needle-like ZnO whisker reinforced Sn1.0Ag0.5Cu composite solders prepared with ultrasonic agitation. Materials and Design, 2021, 210, 110038.	7.0	13
34	The influence of porosity and pore shape on the thermal conductivity of silver sintered joint for die attach. Materials Today Communications, 2021, 29, 102772.	1.9	12
35	Wettability Improvement of Solder in Fluxless Soldering under Formic Acid Atmosphere. , 2021, , .		0
36	Low-pressure micro-silver sintering with the addition of indium for high-temperature power chips attachment. Journal of Materials Research and Technology, 2021, 15, 4541-4553.	5.8	17

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37	Sintered Bonding Process Using Surface Nanostructured Sheet. Hyomen Gijutsu/Journal of the Surface Finishing Society of Japan, 2021, 72, 679-682.	0.2	0
38	Wettability, interfacial reactions, and impact strength of Sn-3.0Ag-0.5Cu solder/ENIG substrate used for fluxless soldering under formic acid atmosphere. Journal of Materials Science, 2020, 55, 3107-3117.	3.7	14
39	Fabrication of Nanoporous Cu Sheet and Application to Bonding for High-Temperature Applications. Journal of Electronic Materials, 2020, 49, 2151-2158.	2.2	19
40	In-situ observation of fluxless soldering of Sn-3.0Ag-0.5Cu/Cu under a formic acid atmosphere. Materials Chemistry and Physics, 2020, 239, 122309.	4.0	17
41	Interfacial transformation of preoxidized Cu microparticles in a formic-acid atmosphere for pressureless Cu-Cu bonding. Journal of Materials Science: Materials in Electronics, 2020, 31, 14635-14644.	2.2	15
42	Isolation and Characterization of Facultative-Anaerobic Antimonate-Reducing Bacteria. Microorganisms, 2020, 8, 1435.	3.6	12
43	Sintered Micro-Silver Paste Doped with Indium for Die Attachment Applications of Power ICs. , 2020, , .		1
44	Mechanical and microstructural enhancements of Ag microparticle-sintered joint by ultrasonic vibration. Journal of Materials Science: Materials in Electronics, 2020, 31, 21711-21722.	2.2	2
45	Microstructure and mechanical properties of the In-48Sn-xAg low-temperature alloy. Journal of Materials Science, 2020, 55, 10824-10832.	3.7	11
46	Effect of surface potential distribution on corrosion behavior of Cu/Al interface in Cu wire bonding applications. Microelectronics Reliability, 2020, 113, 113942.	1.7	5
47	Effect of Zn Addition on Interfacial Reactions and Mechanical Properties Between Eutectic Sn58Bi Solder and ENIG Substrate. Journal of Nanoscience and Nanotechnology, 2020, 20, 106-112.	0.9	3
48	Recent Trends of Micro Joining. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2020, 89, 366-375.	0.1	0
49	Sintered Joint Using Micro-Sized Ag Particles for High-Temperature Application. Journal of Smart Processing, 2020, 9, 259-263.	0.1	0
50	Effect of high-temperature storage at 300 Å°C on sintered layer using micro-sized Ag particles for high-temperature packaging technology. , 2020, , .		0
51	Recent progress in electronic interconnection. Microelectronics Reliability, 2019, 102, 113344.	1.7	0
52	Suppressed Growth of (Fe, Cr, Co, Ni, Cu)Sn ₂ Intermetallic Compound at Interface between Sn-3.0Ag-0.5Cu Solder and FeCoNiCrCu _{0.5} Substrate during Solid-state Aging. Scientific Reports, 2019, 9, 10210.	3.3	12
53	Soldering Process. , 2019, , 191-201.		0
54	Effect of copper over-pad metallization on reliability of aluminum wire bonds. Microelectronics Reliability, 2019, 99, 168-176.	1.7	8

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55	Electrode Formation Using Electrodeposition and Direct Bonding for 3D Integration. , 2019, , 589-604.		0
56	Biosynthesis of bismuth selenide nanoparticles using chalcogen-metabolizing bacteria. Applied Microbiology and Biotechnology, 2019, 103, 8853-8861.	3.6	6
57	Interfacial reaction behavior and mechanical properties of pure aluminum and magnesium alloy dissimilar materials fabricated by hot press and heat treatment. Materials Characterization, 2019, 157, 109879.	4.4	3
58	A Cu-Cu Bonding Method Using Preoxidized Cu Microparticles under Formic Acid Atmosphere. , 2019, , .		5
59	Sn-3.0Ag-0.5Cu/Sn-58Bi composite solder joint assembled using a low-temperature reflow process for PoP technology. Materials and Design, 2019, 183, 108144.	7.0	47
60	Bonding strength of Cu-to-Cu joints using Cu cold spray deposition by an oxidation and reduction process for power device package. , 2019, , .		0
61	Intermetallic compound growth between Sn-Cu-Cr lead-free solder and Cu substrate. Microelectronics Reliability, 2019, 99, 62-73.	1.7	23
62	Microstructure and mechanical properties of Sn-1.0Ag-0.5Cu solder with minor Zn additions. Journal of Materials Science: Materials in Electronics, 2019, 30, 11914-11922.	2.2	15
63	Effects of In Content on the Microstructure and Mechanical Properties of Sn-Bi Alloys During Isothermal Aging. Metals, 2019, 9, 548.	2.3	1
64	Effect of Substrates on Fracture Mechanism and Process Optimization of Oxidation-Reduction Bonding with Copper Microparticles. Journal of Electronic Materials, 2019, 48, 2263-2271.	2.2	22
65	Improved mechanical properties induced by In and In & Zn double additions to eutectic Sn58Bi alloy. Journal of Materials Science: Materials in Electronics, 2019, 30, 7423-7434.	2.2	16
66	Effect of FeCoNiCrCu0.5 High-entropy-alloy Substrate on Sn Grain Size in Sn-3.0Ag-0.5Cu Solder. Scientific Reports, 2019, 9, 3658.	3.3	10
67	The newly developed Sn-Bi-Zn alloy with a low melting point, improved ductility, and high ultimate tensile strength. Materialia, 2019, 6, 100300.	2.7	35
68	Preferred orientation of Bi and effect of Sn-Bi microstructure on mechanical and thermomechanical properties in eutectic Sn-Bi alloy. Materialia, 2019, 6, 100309.	2.7	13
69	Thermomigration induced microstructure and property changes in Sn-58Bi solders. Materials and Design, 2019, 166, 107619.	7.0	35
70	A Computational Thermodynamics-Assisted Development of Sn-Bi-In-Ga Quaternary Alloys as Low-Temperature Pb-Free Solders. Materials, 2019, 12, 631.	2.9	13
71	Effect of bonding temperature on shear strength of joints using micro-sized Ag particles for high temperature packaging technology. , 2019, , .		0
72	The study of Sn-45Bi-2.6Zn alloy before and after thermal aging. , 2019, , .		0

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73	Tin Whisker Growth Mechanism on Tin Plating of MLCCs Mounted with Sn-3.5Ag-8In-0.5Bi Solder in 30Å°C60%RH. , 2019, , .		0
74	Microstructure and Property Changes in Cu/Sn-58Bi/Cu Solder Joints During Thermomigration. , 2019, , .		3
75	Novel polarity effect on intermetallic compound thickness changes during electromigration in Cu/Sn-3.0Ag-0.5Cu/Cu solder joints. Journal of Applied Physics, 2019, 126, .	2.5	15
76	Effects of In and Zn Double Addition on Eutectic Sn-58Bi Alloy. , 2019, , .		2
77	Effects of Ti addition on the microstructure, mechanical properties and electrical resistivity of eutectic Sn58Bi alloy. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2019, 744, 560-569.	5.6	48
78	Bonding strength of Cu/Cu joints using sintering process of micro-sized Cu particles for high-temperature application. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2019, 2019, 000085-000090.	0.2	0
79	Microstructural characterization of Ni-based self-fluxing alloy after selective surface-engineering using diode laser. Applied Surface Science, 2018, 442, 726-735.	6.1	13
80	Characterization of moderately halotolerant selenate- and tellurite-reducing bacteria isolated from brackish areas in Osaka. Bioscience, Biotechnology and Biochemistry, 2018, 82, 173-181.	1.3	19
81	Intermetallic compound formation and mechanical property of SN-CU-XCR/CU lead-free solder joint. , 2018, , .		1
82	Low temperature bonding with high shear strength using micro-sized Ag particle paste for power electronic packaging. Journal of Materials Science: Materials in Electronics, 2018, 29, 3800-3807.	2.2	9
83	Laser-assisted selective fusing of thermal sprayed Ni-based self-fluxing alloys by using high-power diode lasers. Optics and Laser Technology, 2018, 100, 317-324.	4.6	16
84	Interfacial reaction of Sn-Ag-Cu-Ni solder/Cu joints by laser process. , 2018, , .		1
85	Textile-Integrated Stretchable Structures for Wearable Wireless Platforms. , 2018, , .		1
86	Fabrication and Performance Evaluation of Carbon-based Stretchable RFID Tags on Textile Substrates. , 2018, , .		3
87	Failure analysis on Mobile Phone Batteries and Accessories. , 2018, , .		0
88	Control for Au-Ag Nanoporous Structure by Electrodeposition and Dealloying. , 2018, , .		0
89	Shear properties of In-Bi alloy joints with Cu substrates during thermal aging. Microelectronics Reliability, 2018, 88-90, 795-800.	1.7	2
90	Improvement in Thermomechanical Reliability of Low Cost Sn-Based BGA Interconnects by Cr Addition. Metals, 2018, 8, 586.	2.3	7

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91	Low Temperature Flip Chip Bonding Using Squeegee-Embedded Au Nanoporous Bump Activated by VUV/O ₃ Treatment. Journal of Electronic Materials, 2018, 47, 5952-5958.	2.2	1
92	Corrosion and Leaching Behaviours of Sn-0.7Cu-0.05Ni Lead-Free Solder in 3.5%wt.% NaCl Solution. International Journal of Corrosion, 2018, 2018, 1-11.	1.1	8
93	Microstructure and mechanical properties of indium-bismuth alloys for low melting-temperature solder. Journal of Materials Science: Materials in Electronics, 2018, 29, 16460-16468.	2.2	4
94	Transient Liquid Phase Bonding of Magnesium Alloy AZ31 Using Cu Coatings and Cu Coatings with Sn Interlayers. Metals, 2018, 8, 60.	2.3	12
95	Mechanical properties of Sn-Bi-In-Ga low melting temperature solder alloys. , 2018, , .		0
96	Improvement of Mechanical Properties of Zn-Added Sn58Bi Alloy by Zn Segregation on the Sn-Bi Phase Boundaries During Thermal Aging. , 2018, , .		1
97	High Reliability Sintered Silver-Indium Bonding with Anti-Oxidation Property for High Temperature Applications. , 2018, , .		5
98	Development of Low-Temperature, Pressureless Copper-to-Copper Bonding by Microfluidic Electroless Interconnection Process. , 2018, , .		2
99	Improvement in the mechanical properties of eutectic Sn58Bi alloy by 0.5 and 1%wt% Zn addition before and after thermal aging. Journal of Alloys and Compounds, 2018, 765, 1243-1252.	5.5	56
100	A Preface. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2018, 87, 498-498.	0.1	0
101	Lead-Free High Temperature Bonding Processes for Next Generation Power Module Packaging. Journal of Smart Processing, 2018, 7, 28-31.	0.1	0
102	Effect of temperature and substrate on shear strength of the joints formed by sintering of micro-sized Ag particle paste without pressure. Journal of Materials Science: Materials in Electronics, 2017, 28, 7292-7301.	2.2	10
103	Brazing Graphite to Aluminum Nitride for Thermal Dissipation Purpose. Advanced Engineering Materials, 2017, 19, 1600876.	3.5	11
104	Thermal stability of low-temperature sintered joint using Sn-coated Cu particles during isothermal aging at 250°C. Journal of Materials Science: Materials in Electronics, 2017, 28, 12606-12616.	2.2	9
105	Effect of Bonding Temperature on the Joining of Ti-6Al-4V Alloy Using Cu Coatings and Sn Interlayers. Journal of Materials Engineering and Performance, 2017, 26, 407-417.	2.5	4
106	Pressureless sintering bonding using hybrid microscale Cu particle paste on ENIG, pure Cu and pre-oxidized Cu substrate by an oxidation-reduction process. Journal of Materials Science: Materials in Electronics, 2017, 28, 5554-5561.	2.2	18
107	Effect of substrate metallization on the impact strength of Sn-Ag-Cu solder bumps fabricated in a formic acid atmosphere. , 2017, , .		6
108	Intermetallic compound formation and mechanical property of Sn-Cu-xCr/Cu lead-free solder joint. Journal of Alloys and Compounds, 2017, 728, 992-1001.	5.5	22

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109	Influence of ENIG defects on shear strength of pressureless Ag nanoparticle sintered joint under isothermal aging. <i>Microelectronics Reliability</i> , 2017, 76-77, 420-425.	1.7	9
110	Low temperature solid-state bonding using Sn-coated Cu particles for high temperature die attach. <i>Journal of Alloys and Compounds</i> , 2017, 695, 2165-2172.	5.5	60
111	Interfacial reaction, ball shear strength and fracture surface analysis of lead-free solder joints prepared using cobalt nanoparticle doped flux. <i>Journal of Alloys and Compounds</i> , 2017, 695, 981-990.	5.5	26
112	Inkjet-printed antenna-electronics interconnections in passive UHF RFID tags. , 2017, , .		2
113	Effect of indium on deformation of binary In-Bi alloys. , 2017, , .		1
114	The evaluation of mechanical properties of Sn58BiXTi solder by tensile test. , 2017, , .		1
115	Impact strength of Sn-Ag-Cu/Cu solder bumps formed by an induction heating method. , 2017, , .		0
116	Effect of bonding conditions on shear strength of joints at 200 Å°C using Sn-coated Cu particle. , 2017, , .		0
117	Effect of Thermal Aging on the Impact Strength of Soldered Bumps under Formic Acid Atmosphere. <i>Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society</i> , 2017, 35, 127s-131s.	0.5	4
118	Transmission Electron Microscopy Investigation on the Oxidation Behavior of Electroless Ni/Immersion Au Surface Finish at 250 Å°C. <i>Journal of Nanoscience and Nanotechnology</i> , 2017, 17, 8522-8527.	0.9	5
119	A Preface. <i>Yosetsu Gakkai Shi/Journal of the Japan Welding Society</i> , 2017, 86, 431-431.	0.1	0
120	Effect of isothermal aging at 250 Å°C on shear strength of joints using Sn-Coated Cu particle paste for high-temperature application. <i>Additional Conferences (Device Packaging HiTEC HiTEN & CICMT)</i> , 2017, 2017, 000202-000206.	0.2	0
121	Effect of Zn Addition on Interfacial Reactions Between Sn-Bi Solder and Cu Substrate. <i>Materials Transactions</i> , 2016, 57, 1272-1276.	1.2	14
122	Bonding process without pressure using a chestnut-burr-like particle paste for power electronics. , 2016, , .		0
123	Pressureless Bonding by Micro-Sized Silver Particle Paste for High-Temperature Electronic Packaging. <i>Materials Transactions</i> , 2016, 57, 1209-1214.	1.2	16
124	Reliability of Ag Nanoporous Bonding Joint for High Temperature Die Attach under Temperature Cycling. <i>Materials Transactions</i> , 2016, 57, 1192-1196.	1.2	8
125	Low-pressure Cu-Cu bonding using in-situ surface-modified microscale Cu particles for power device packaging. <i>Scripta Materialia</i> , 2016, 120, 80-84.	5.2	112
126	The shear strength of transient liquid phase bonded Snâ€Bi solder joint with added Cu particles. <i>Advanced Powder Technology</i> , 2016, 27, 1000-1005.	4.1	34

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127	Experimental study on antenna " IC interconnections for electro-textile RFID tags. , 2016, , .		1
128	Improved Joint Strength with Sintering Bonding Using Microscale Cu Particles by an Oxidation-Reduction Process. , 2016, , .		5
129	Investigation of connecting techniques for high temperature application on power modules. , 2016, , .		1
130	Effect of magnetic flux density on Sn crystallographic orientation in a solder joint system. Journal of Materials Science: Materials in Electronics, 2016, 27, 3710-3714.	2.2	5
131	Low temperature bonding using microscale Cu particles coated with thin Sn layers at 200 °C. , 2016, , .		2
132	Correlation between microstructure and mechanical properties of Sn-Bi-X solders. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 651, 831-839.	5.6	96
133	Transient liquid phase bonding of Sn-Bi solder with added Cu particles. Journal of Materials Science: Materials in Electronics, 2016, 27, 4232-4244.	2.2	38
134	Thermally stable Cu 3 Sn/Cu composite joint for high-temperature power device. Scripta Materialia, 2016, 110, 101-104.	5.2	77
135	A Preface. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2016, 85, 331-331.	0.1	0
136	Improvement of Joint Reliability of Sn-Ag-Cu Solder Bumps on Cu by a Laser Process. Materials Transactions, 2015, 56, 1025-1029.	1.2	9
137	Shear strength of Cu-to-Cu joints using mixed Ag particle paste. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2015, 33, 75s-78s.	0.5	1
138	Effect of isothermal aging on microstructure and joint strength of Ag nanoporous bonding for high temperature die attach. , 2015, , .		1
139	Improved low temperature gold-gold bonding using nanoporous powder bump using vacuum ultraviolet irradiation pre-treatment. , 2015, , .		2
140	Microscale Ag particle paste for sintered joints in high-power devices. Materials Letters, 2015, 161, 231-233.	2.6	47
141	Effect of porous copper on the properties of electrically conductive adhesives. Journal of Materials Science: Materials in Electronics, 2015, 26, 7771-7779.	2.2	7
142	Effects of bonding temperature on microstructure, fracture behavior and joint strength of Ag nanoporous bonding for high temperature die attach. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2015, 645, 264-272.	5.6	36
143	Ball shear strength and fracture modes of lead-free solder joints prepared using nickel nanoparticle doped flux. Electronic Materials Letters, 2015, 11, 452-456.	2.2	10
144	Reliability of copper wire bonds on a novel over-pad metallization. Japanese Journal of Applied Physics, 2015, 54, 05EC01.	1.5	1

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145	Formation and growth of intermetallic compound layers at the interface during laser soldering using Sn-3Ag-Cu solder on a Cu Pad. Journal of Materials Processing Technology, 2015, 215, 6-11.	6.3	70
146	Microstructure of Transient Liquid Phase Sintering Joint by Sn-Coated Cu Particles for High Temperature Packaging. International Symposium on Microelectronics, 2015, 2015, 000449-000452.	0.0	2
147	A Review of Ag Paste Bonding for Automotive Power Device Packaging. Journal of the Microelectronics and Packaging Society, 2015, 22, 15-23.	0.1	5
148	A Preface. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2015, 84, 178-178.	0.1	0
149	Effects of Joining Conditions on Cu/Cu Joint Using Chestnut-burr-like Micro-sized Ag Particles. Journal of Smart Processing, 2014, 3, 240-245.	0.1	0
150	Microstructure of lead-free solder bumps using laser reflow soldering. IOP Conference Series: Materials Science and Engineering, 2014, 61, 012038.	0.6	1
151	Investigation of Formation and Growth Behavior of Cu/Al Intermetallic Compounds during Isothermal Aging. Transactions of the Japan Institute of Electronics Packaging, 2014, 7, 1-7.	0.4	9
152	Effects of In and Ni Addition on Microstructure of Sn-58Bi Solder Joint. Journal of Electronic Materials, 2014, 43, 4158-4170.	2.2	46
153	Relationship between bonding conditions and strength for joints using a Au nanoporous sheet. , 2014, , .		2
154	Effect of joining conditions on the joint strength of Ag nanoporous bonding. , 2014, , .		2
155	Effect of isothermal aging on the growth behavior of Cu/Al intermetallic compounds. , 2014, , .		0
156	Low-temperature gold-gold bonding using selective formation of nanoporous powders for bump interconnects. , 2014, , .		3
157	Thermal stability of electroless nickel/immersion gold surface finish for direct bond copper. , 2014, , .		1
158	Impact strength of Sn-3.0Ag-0.5Cu solder bumps during isothermal aging. Microelectronics Reliability, 2014, 54, 1583-1591.	1.7	42
159	Microstructural change of Ag nanoporous bonding joint and interdiffusion of Cu / Ag during thermal aging. , 2014, , .		0
160	Silver nanoporous sheet for solid-state die attach in power device packaging. Scripta Materialia, 2014, 92, 43-46.	5.2	50
161	Copper-Filled Electrically Conductive Adhesives with Enhanced Shear Strength. Journal of Materials Engineering and Performance, 2014, 23, 3371-3378.	2.5	15
162	Influence of post-curing and coupling agents on polyurethane based copper filled electrically conductive adhesives. Journal of Materials Science: Materials in Electronics, 2013, 24, 2077-2081.	2.2	9

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163	Fabrication of nanoporous silver and microstructural change during dealloying of melt-spun Al-20at.%Ag in hydrochloric acid. Journal of Materials Science, 2013, 48, 5645-5652.	3.7	24
164	Low-Temperature Au-Au Bonding Using Nanoporous Au-Ag Sheets. Japanese Journal of Applied Physics, 2013, 52, 050204.	1.5	8
165	Explanation of impact load curve in ball impact test in relation to thermal aging. Microelectronics Reliability, 2013, 53, 2005-2011.	1.7	6
166	Influence of Joining Conditions on Bonding Strength of Joints: Efficacy of Low-Temperature Bonding Using Cu Nanoparticle Paste. Journal of Electronic Materials, 2013, 42, 1260-1267.	2.2	88
167	Coarsening of Bi phase and intermetallic layer thickness in Sn-58Bi-X (X=In and Ni) solder joint. , 2013, , .		3
168	Properties of Phenolic-Based Ag-Filled Conductive Adhesive Affected by Different Coupling Agents. Journal of Adhesion, 2013, 89, 847-858.	3.0	16
169	Effects of minor alloying additive on the shear strength of Sn-58Bi solder joint. International Symposium on Microelectronics, 2013, 2013, 000100-000103.	0.0	2
170	Using nano-porous Au-Ag sheets as a joint layer for low-temperature Au-Au bonding. , 2012, , .		1
171	Surfactant-Free Synthesis of Copper Particles for Electrically Conductive Adhesive Applications. Journal of Electronic Materials, 2012, 41, 2527-2532.	2.2	14
172	Development of Lead-free Solder and Emerging Trend of New Joining Material. Yosetsu Gakkai Shi/Journal of the Japan Welding Society, 2012, 81, 45-57.	0.1	3
173	Effect of different copper fillers on the electrical resistivity of conductive adhesives. Journal of Materials Science: Materials in Electronics, 2011, 22, 538-544.	2.2	13
174	Electrical reliability of different alloying content on copper alloy fillers in electrically conductive adhesives. Journal of Materials Science: Materials in Electronics, 2011, 22, 735-740.	2.2	10
175	Solderability of metallic glass. Welding International, 2011, 25, 505-508.	0.7	2
176	Interfacial Reaction between Sn-3.0Ag-0.5Cu Solder/Co-P Plating and Ni-Co-P Plating. Yosetsu Gakkai Ronbunshu/Quarterly Journal of the Japan Welding Society, 2011, 29, 142s-146s.	0.5	1
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